

適用於化學銅與電鍍銅的清潔劑

Cleaner for Both Electroless and Electroplated Copper Surface



RONACLEAN™ EVP221 / 222S Cleaner

RONACLEAN™ EVP-221 cleaner is an acidic immersion type cleaner, has superior wetting ability and lower surface tension. It is effective in removing resist residues that may be left from incomplete development of dry film on an electroless or electroplated copper surface. RONACLEAN EVP-222S cleaner is an acidic sprayable product, developed for horizontal and new vertical-in-line plating equipment on IC Substrate and HDI PCB applications.

RONACLEAN EVP-221是浸泡式酸性清潔劑, 能表現出優異的濕潤效果, 並有較低的表面張力. 同時對於乾膜工序後所殘留的光阻, 亦有良好的清潔效果; RONACLEAN EVP-222S 一款噴灑型的酸性清潔劑產品, 可搭配水平和新型垂直傳動電鍍設備生產IC基板和HDI板.

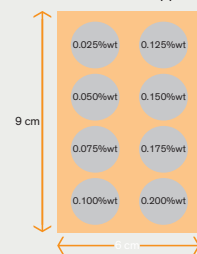
Advantage of RONACLEAN™ EVP 221/ 222S RONACLEAN™ EVP 221/ 222S具備以下卓越的特性:

- Readily removes oils, light oxides and soils, improved rinsibility
易於去除油脂類, 氧化物和磷汗, 清洗性能顯著提升
- Contains neither Alkyl Phenol Ethoxylates (APE) nor strong chelating agent
不含烷基酚聚氧乙烯醚或強效螯合劑
- Low-foaming
少泡沫
- Ease of waste treatment
廢水容易處理
- Good compatibility with Dow Electronic Materials acid copper electrolytes
與陶氏酸性銅電鍍液有著良好的相容性

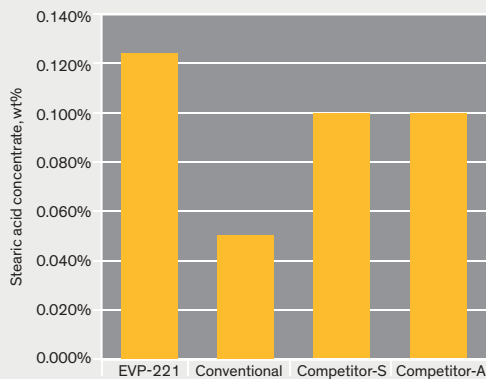
Detergency of EVP221

Remove stearic acid stain from clad copper surface

Stearic Acid solute droplet

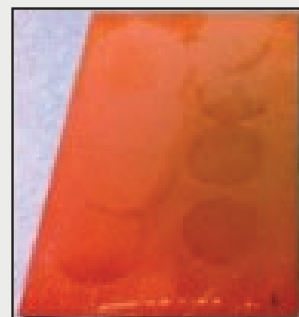


Dwell Time: 2 min
Temp.: 40 °C
Agitation: Back & forward movement



Panel after cleaner treatment:

Conventional Result



EVP221 Result

